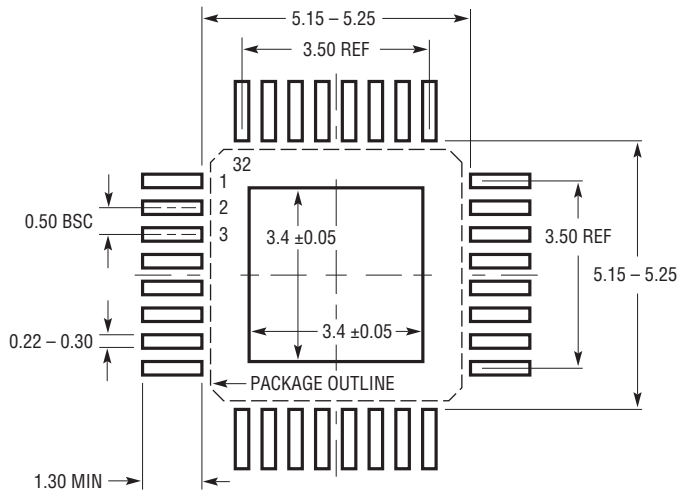
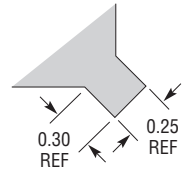
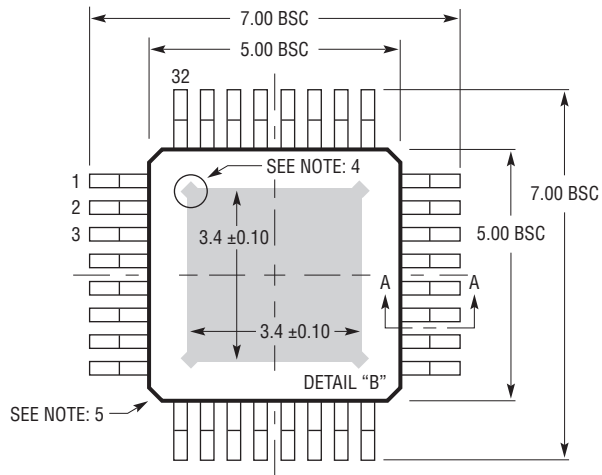


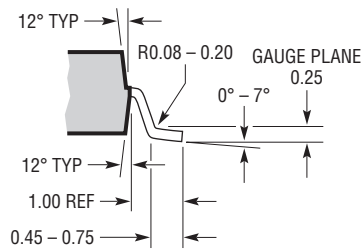
LUE Package
32-Lead Plastic Exposed Pad TQFP (5mm × 5mm)
 (Reference LTC DWG # 05-08-1986 Rev Ø)



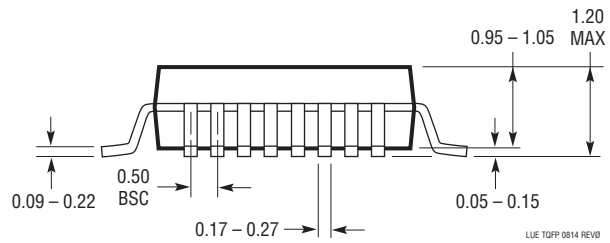
RECOMMENDED SOLDER PAD LAYOUT
APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED



DETAIL "B"
CORNER TAIL IS PART OF
THE LEADFRAME FEATURE.
FOR REFERENCE ONLY
NO MEASUREMENT PURPOSE



SECTION A - A



LUE TQFP 0814 REV0

NOTE:

- NOTE:
1. DRAWING CONFORMS TO JEDEC #MS-026 PACKAGE OUTLINE
 2. DIMENSIONS ARE IN MILLIMETERS
 3. DIMENSIONS OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.25mm ON ANY SIDE, IF PRESENT

4. PIN-1 IDENTIFIER IS A MOLDED INDENTATION
5. EXACT SHAPE OF EACH CORNER IS OPTIONAL
6. DRAWING IS NOT TO SCALE